

Abstract

An image pick-up module, especially for an endoscope, comprises an electronic image sensor, a single-piece circuit board which is electrically bonded to the image sensor, with at least one cable leading away from the circuit board being further electrically bonded to the circuit board. The circuit board has at least three sections, with a first section and a second section extending in spaced relation one to the other and obliquely or crosswise to the image sensor and a third section being arranged between the first and the second section. In order to provide for strain relief of the at least one cable, it is proposed that the image sensor be arranged on one side of the circuit board opposite the third section. In a method for assembling the image pick-up module the circuit board initially has the form of a planar board blank comprising at least three sections that can be folded along flexible connecting sections whereby the at least one cable is bonded to the board blank, whereafter the board blank is folded in such a way that a third section is located between a first section and a second section, and finally the image sensor is bonded to the circuit board at an end of the circuit board opposite the third section.